



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

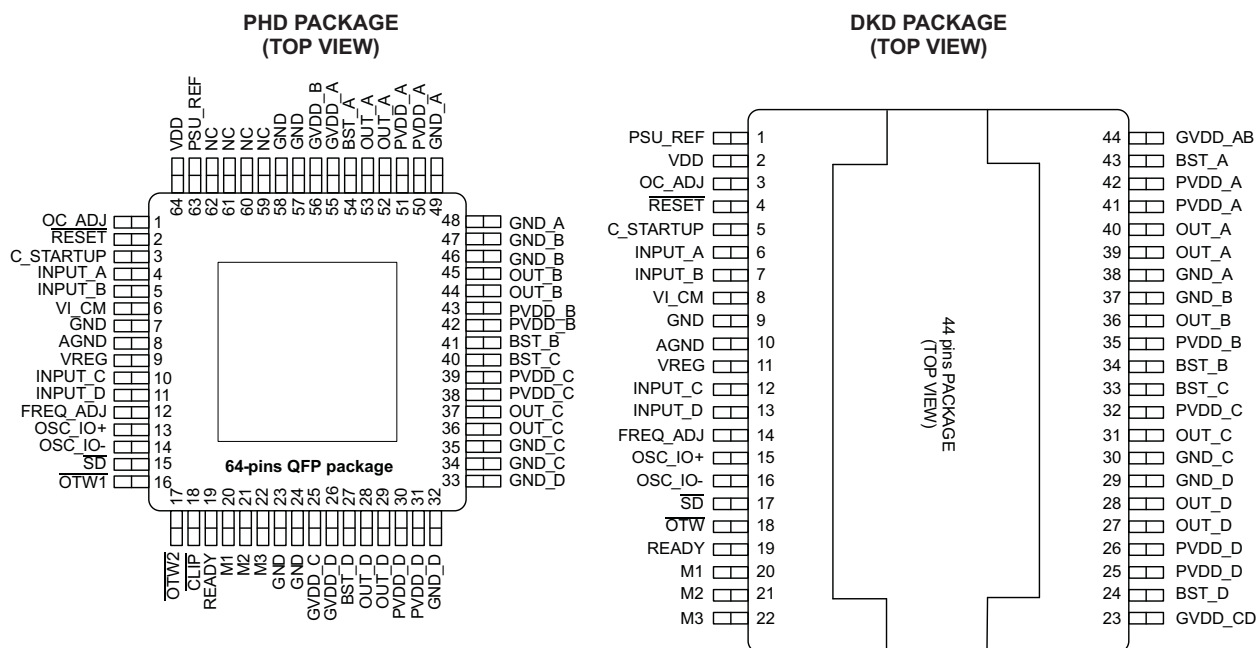
DEVICE INFORMATION

Terminal Assignment

The TAS5615 is available in two thermally enhanced packages:

- 64-Pin QFP (PHD) Power Package
- 44-Pin PSOP3 package (DKD)

The package type contains a heat slug that is located on the top side of the device for convenient thermal coupling to the heat sink.



PIN ONE LOCATION PHD PACKAGE

